

TFT-LCD PRODUCT SPECIFICATION

PART NUMBER:	USMP-TT024Q-01B
DESCRIPTION:	2.4" TFT LCD with
DESCRIPTION:	240 x 320 resolution,
	White LED B/L and
	8-bit interface for i-80system Interface.

ISSUE DATE	APPROVED BY	CHECKED BY	PREPARED BY
	(Customer Use Only)		
PROPRIETARY NOTE:	THIS SPECIFICATION IS THE PROPERTY OF COPIED WITHOUT THE WRITTEN PERMINERO		AND MUST BE RETURNED TO



History of Version

Date	Ver.	Edi.	Description	Page	Design by
2009/7/21	01	001	New Drawing	-	Binbin
2009/7/30	01	002	Modify FPC Pins	Page11,Appendix	Binbin
2009/8/3	01	003	Modify FPC Pins	Appendix	Binbin
2009/10/28	01	004	New Sample	-	violin

Total: 24 Page



Contents

1. SPECIFICATIONS

- 1.1 Features
- 1.2 Mechanical Specifications
- 1.3 Absolute Maximum Ratings
- 1.4 DC Electrical Characteristics
- 1.5 Optical Characteristics
- 1.6 Backlight Characteristics

2. MODULE STRUCTURE

- 2.1 Counter Drawing
- 2.2 Interface Pin Description
- 2.3 Timing Characteristics

3. QUALITY ASSURANCE SYSTEM

- 3.1 Quality Assurance Flow Chart
- 3.2 Inspection Specification

4. RELIABILITY TEST

4.1 Reliability Test Condition

5. PRECAUTION RELATING PRODUCT HANDLING

- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- 5.4 Terms of Warranty

Appendix: 1. LCM Drawing



1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Item	Standard Value
Display Type	240 * (R · G · B) * 320 Dots
LCD Type	a-Si TFT , Positive , Transmissive
Screen size(inch)	2.4 (Diagonal)
Viewing Direction	12 O'clock
Color configuration	R.G.B. vertical stripe
Backlight	White LED
Interface	8-bit interface for i-80system
Other(controller / driver IC)	ST7781

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	42.32 (W) * 60.06 (L) * 2.4 (H)	mm

LCD Panel

Item	Standard Value	Unit
Viewing Area	38.32 (W) * 50.56 (L)	mm
Active Area	36.72 (W) * 48.96 (L)	mm

Note: For detailed information please refer to LCM drawing



1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
System Power Supply Voltage	VDD	-	-0.3	+4.6	V
Oystem Fower Supply Voltage	VGH-VGL	1	-0.3	+30	V
Input Voltage	VIN	1	0.5	VDD+0.5	V
Output Volatage	VO	-	0.5	VDD+0.5	V
Operating Temperature	T _{OP}	-	-20	+70	°C
Storage Temperature	T _{ST}	-	-30	+80	°C
Storage Humidity	H _D	Ta ≦ 40 °C	20	90	%RH

1.4 DC Electrical Characteristics

Module

GND = 0V, Ta = $25^{\circ}C$

- Inodaic				0.10	v, ia 20 0	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage1	VDD	-	-	2.8	-	V
Input High Voltage	V _{IH}	-	0.7*VDD	-	VDD	V
Input Low Voltage	V _{IL}	-	0	-	0.3*VDD	V
Output High Voltage	V _{OH}	IOH=-0.1mA	0.8*VDD	ı	VDD	V
Output Low Voltage	V _{OL}	IOL=+0.1mA	0	-	0.2*VDD	V
Supply Current	IDD	VDD= 2.8V, Pattern=black *1	-	6.5	10	mA

Note1: Maximum current display



1.5 Optical Characteristics

TFT LCD Panel

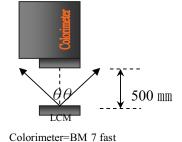
VDD = 2.8V, Ta=25°C

						, -		
Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Response tin	ne	Tr + Tf	Ta = 25°C θX, θY = 0°	-	35	55	ms	Note2
	Тор	θΥ+		-	50	-		
Viewing angle	Bottom	θΥ-	CR ≥ 10	-	45	-	Deg.	Note4
viewing angle	Left	θΧ-	CIV = 10	-	50	-	Deg.	NOIGH
	Right	θX+		-	50	-		
Contrast rati	0	CR		190	210	-	-	Note3
	White	Х		0.229	0.279	0.329		
		Υ	Ta = 25°C θX , θY = 0°	0.264	0.314	0.364	_	Note1
0-1	Red	Х		0.573	0.623	0.673		
Color of CIE Coordinate		Υ		0.287	0.337	0.387		
(With B/L)	Green	Χ		0.287	0.337	0.387		
(******=/=/	Green	Y		0.545	0.585	0.535		
	Blue	X		0.098	0.148	0.198		
	Diue	Υ		0.034	0.084	0.134		
Average Brightness								
Pattern=white display		IV	IF= 60mA	140	180	-	cd/m ²	Note1
(With B/L)								
Uniformity (With B/L)		△B	IF=60mA	80	-	-	%	Note1

Note1:

- $1 : \triangle B=B(min) / B(max) \times 100\%$
- 2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25° C $\pm 5^{\circ}$ C / $60\pm 20\%$ R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: $500 \pm 50 \text{ mm}$, $(\theta = 0^{\circ})$
 - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%



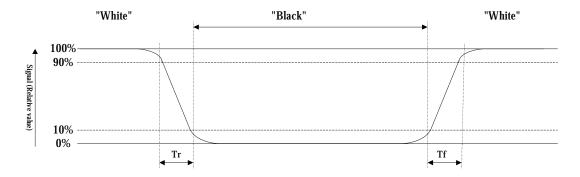




Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

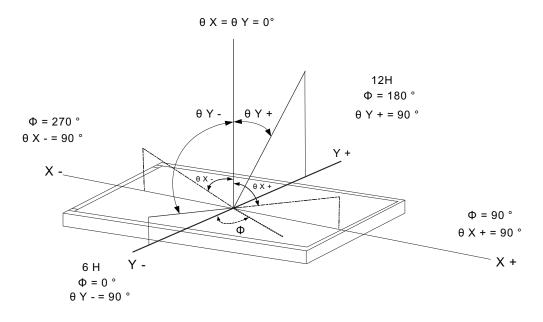
Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle:

Refer to figure as below:





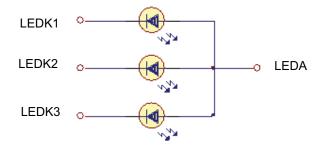
1.6 Backlight Characteristics

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°ℂ	-	90	mA
Forward Voltage	VF	Ta =25°ℂ	-	4	V
Reverse Voltage	VR	Ta =25°ℂ	-	5	V

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF= 60mA	-	3.5	-	V
Average Brightness (without LCD & T/P)	IV		2500	2800	-	cd/m ²
Color of CIE Coordinate	X	IF= 60mA	0.24	-	0.30	
(without LCD & T/P)	Y		0.24	-	0.30	-
Color			White			





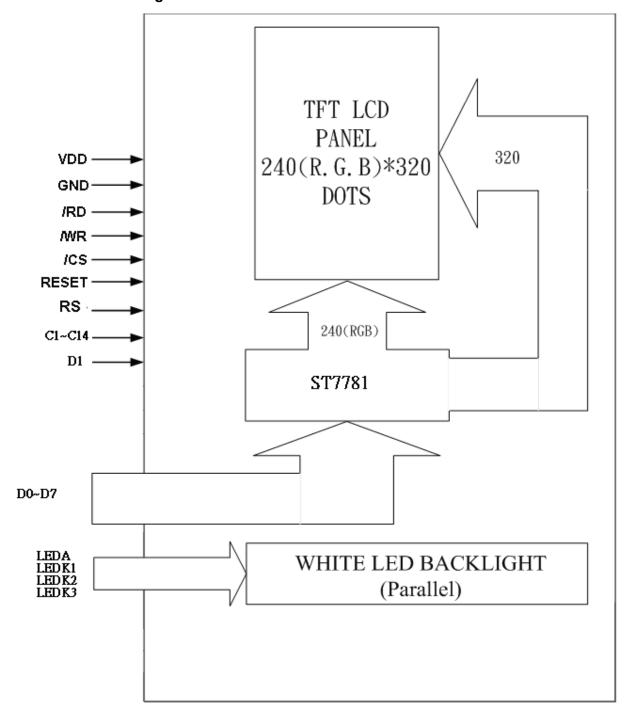
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





2.2 Interface Pin Description

Pin No.	Symbol	Function				
1	GND	System ground.(0V)				
2	RESET	Reset input pin. When RESET is "L", initialization is executed.				
3	D7	Bi-directional data bus.				
4	D6	Bi-directional data bus.				
5	D5	Bi-directional data bus.				
6	D4	Bi-directional data bus.				
7	D3	Bi-directional data bus.				
8	D2	Bi-directional data bus.				
9	D1	Bi-directional data bus.				
10	D0	Bi-directional data bus.				
11	/RD	Read signal input, active "L".				
12	WR	Write signal input, active "L".				
13	RS	Command/Display data selection. 0:Command 1:Display data				
14	/CS	Chip select signal, active "L".				
15	VDD C1	Place a 1uF/10V capacitor to GND.				
16	VCOMH C2	VCOMH pad. Place a 1uF/10V capacitor to GND.				
17	VCOML C3	VCOML pad. Place a 1uF/10V capacitor to GND.				
18	GVDD C4	GVDD pad. Place a 1uF/10V capacitor to GND.				
19	VCL C5	VCL pad. Place a 1uF/10V capacitor to GND.				
20	AVDD C6	AVDD pad. Place a 1uF/10V capacitor to GND.				
21	VCI1 C7	VCI1 pad. Place a 1uF/10V capacitor to GND.				
22	C8N	DI 4 5/40)/ '(1 00D				
23	C8P	Place a 1uF/10V capacitor between C8N and C8P.				
24	C9N	Diagonal 44F/40V/ congoitar historica CON and COD				
25	C9P	Place a 1uF/10V capacitor between C9N and C9P.				
26	VGL C10 D1	VGL pad. Place a Diode(VF<0.47V IF=200mA) to GND ("+"connect to VGL & "-"connect to GND) .Place a 1uF/25V capacitor to GND.				

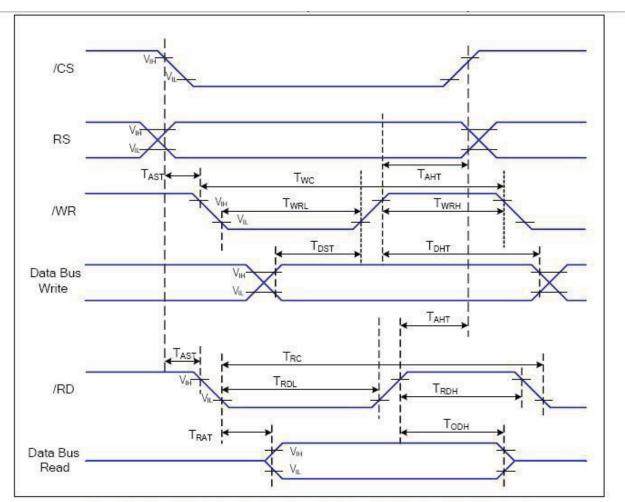


Pin No.	Symbol	Function	
27	VGH C11	VGH pad. Place a 1uF/25V capacitor to GND.	
28	C12N	Place a 1uF/10V capacitor between C12N and C12P.	
29	C12P	Flace a Tur/Tov capacitor between C12N and C12r.	
30	C13N	Place a 1µE/25V capacitor between C13N and C13P	
31	C13P	Place a 1uF/25V capacitor between C13N and C13P.	
32	C14N	Diago a 1uE/25V consoiter between C14N and C14D	
33	C14P	Place a 1uF/25V capacitor between C14N and C14P.	
34	LEDA	Power supply for LED Backlight Anode input.	
35	LEDK1	Power supply for LED Backlight Cathode input.	
36	LEDK2	Power supply for LED Backlight Cathode input.	
37	LEDK3	Power supply for LED Backlight Cathode input.	
38	VDD	Power supply.(2.8V) .	



2.3 Timing Characteristics

80-System Bus Interface

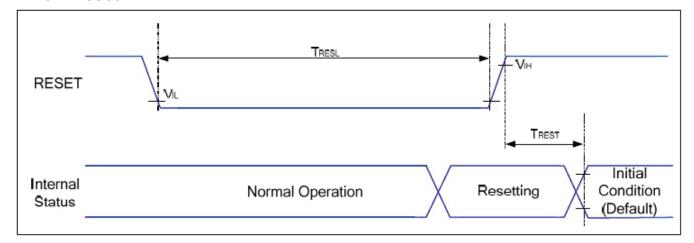


VDD=2.8V GND=0V Ta=25 %

Signal	Symbol	Parameter	Min	Max	Unit	Description
De	TAST	Address Setup Time	10	2	ns	-0
RS TAHT		Address Hold Time (Write/Read)	5	14	ns	
	Twc	Write Cycle	100	<u></u>	ns	
WR	T _{WRH}	Control Pulse "H" Duration	50		ns	
	T _{WRL}	Control Pulse "L" Duration	50	Ü	ns	
	T _{RC}	Read Cycle	300	8	ns	
/RD	T _{RDH}	Control Pulse "H" Duration	150	k g	ns	
	T _{RDL}	Control Pulse "L" Duration	150	5	ns	
	T _{DST}	Data Setup Time	10		ns	T _{RAT} , T _{RATFM} : 3K ohm
D0 D0	TDHT	Data Hold Time	15	Œ	ns	Pullup or Down and 30pF
D0~D7	T _{RAT}	Read Access Time	188	100	ns	Parallel Cap. To GND. Todh: 3K ohm Pullup or
	T _{ODH}	Output Disable Time	50	<u>.</u>	ns	Down.



LCD Reset



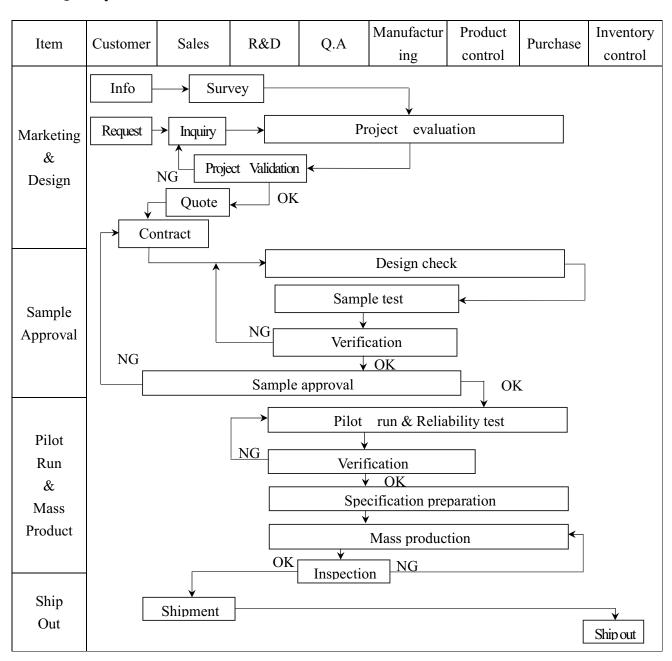
VDD=2.8V GND=0V Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
RESET	TRESL	Reset Low Level Width	1:	1	ms	
KESET	T _{REST}	Reset Complete Time	1:		ms	

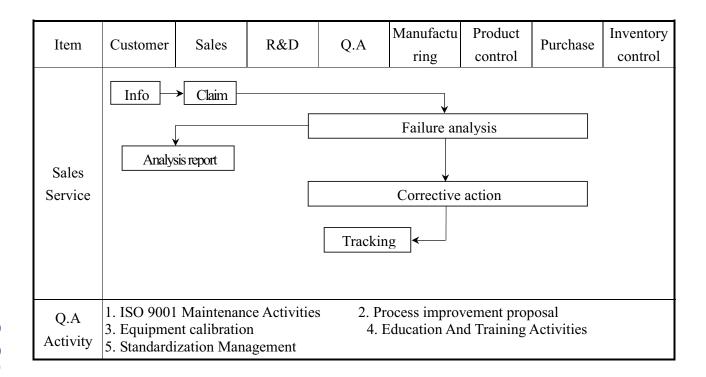


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

◆Scope : The document shall be applied to TFT-LCD Module for less than 3, 5" (Ver.B01).

◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment: Gauge、MIL-STD、 Sample

◆Defect Level: Major Defect AQL: 0,4; Minor Defect AQL: 1,5

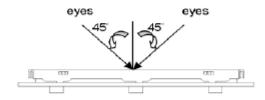
◆OUT Going Defect Level: Sampling.

Standard of the product appearance test :

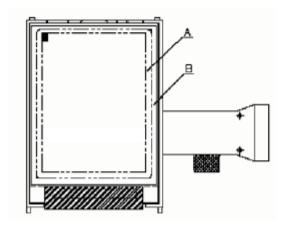
a. Manner of appearance test:

(1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.

(2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area: viewing area

B area: Outside of viewing area

(4). Standard of inspection: (Unit: mm)



◆Specification For TFT-LCD Module Less Than 3, 5":

(Ver. 02)

Leve		on	Criteri			Item	NO
Majo	of	t with work order of		e part nu roduction	1		
Majo			luct types.	ixed prod	1. 2 Mi	01 Product condition	
Majo			in inverse direction.	sembled	1. 3 As		
Majo	2. 1The quantity is inconsistent with work order of production.			2. 1Th	Quantity	02	
Majo	3. 1 Product dimension and structure must conform to structure diagram.					Outline dimension	03
Majo		ı.	e character and icon	issing line	4. 1 Mi		
Majo	4. 2 No function or no display.						
Majo	4. 3 Display malfunction.				Electrical Testing	04	
Majo	4. 4 LCD viewing angle defect.						
Majo	ons.	product specifications.	nsumption exceeds	irrent co	4. 5 Cu		
	ty)	Acceptance (Q'ty)	Item				
		≤ 2	Bright Dot				
		≦ 3	Dark Dot	Dot		Dot defect	
		≦ 2	Joint Dot	Defect		(Bright dot \	
Mino		≦ 3	Total			Dark dot)	05
	, Green and	5. 1 Inspection pattern: full white, full black, Red, Green and			On -display		
			blue screei				
			as dot defect if def				
			e between two dot o				



◆Specification For TFT-LCD Module Less Than 3, 5":

(Ver. 02)

NO	Item		Cri	terion		Level
06	Black or white dot \ scratch \ contamination Round type \[\frac{1}{Y} \] \[\frac	0. 15 < 0. 20 <	0.03 < W	• display) : W) ≤ 0.03	eptance (Q'ty) Ignore 2 2 0 3	Minor
07	Polarizer Bubble	0.20 <	diameter : Φ) $\Phi \leq 0.20$ $\Phi \leq 0.50$ $\Phi > 0.50$ otal	Acc	Ignore 3 0 3	Minor



◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item		Criterion		Level
		Z: The th	ickness of crack V	Y : The width of crack. W : terminal length a : LCD side length	
		1	1 glass chip: p on panel surface and cra	nck between panels:	
		SP-	1	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	
80	The crack of glass	51-	Y [OK]	[NG]	Minor
			Seal width	X	
		X	Y	z	
		≤ a	Crack can't enter viewing area	≤1/2 t	
		≦ a	Crack can't exceed the half of SP width.	$1/2 t < Z \leq 2 t$	



NO	Item		Criterion		Level
		Z: The th	ickness of crack V ckness of glass a	Y : The width of crack. V : terminal length a : LCD side length	
		8. 1. 2 Cor	ner crack:	z	
		≤1/5 a	Crack can't enter viewing area	Z ≤ 1/2 t	
		≤1/5 a	Crack can't exceed the half of SP width.	$1/2 t < Z \leq 2 t$	
08	The crack of glass	3000000 87 200 8	sion over terminal: p on electrode pad:	²⁰	_ Mino
		. 3	Z	X Y Z	

	X	Y	Z
Front	≦ a	≤ 1/2 W	≦ t
Back	≦ a	≦ W	≤ 1/2 t



◆Specification For TFT-LCD Module Less Than 3, 5": (Ver. 02) NO Item Criterion Level Symbols: Y: The width of crack. X: The length of crack Z: The thickness of crack W: terminal length t: The thickness of glass a: LCD side length 8. 2. 2 Non-conductive portion: X Y Z The crack of 08 Minor $\leq 1/3$ a glass $\leq W$ ≦t ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. 8. 2. 3 Glass remain: X Y Z ≤ 1/3 W ≦ a ≦t



♦ Specification For TFT-LCD Module Less Than 3.5":

(Ver. 02)

NO	Item	Criterion	Level
		9. 1 Backlight can't work normally.	Major
09	Backlight elements	9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
		10. 1 Pin type \quantity \quantity \dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC .	Major
10	General	10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10	appearance	10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is $~\leq 1, 5$ mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

Ver.02

4.1	Reliability lest Con					
NO.	TEST ITEM	TEST CO	NDITION			
1	High Temperature Storage Test	Keep in +80 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
2	Low Temperature Storage Test	Keep in -30 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
3	High Temperature / High Humidity Storage Test	-	Keep in +60°C / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)			
		Air Discharge:	Contact Discharge:			
		Apply 2KV with 5 times	Apply 250V with 5 times			
		Discharge for each polarity +/-	discharge for each polarity +/-			
4	ESD Test	 Temperature ambiance: 15°C ~35°C Humidity relative: 30%~60% 				
7	ESD lest	3. Energy Storage Capacitance(Cs+Cd): 150pF±10%				
		4. Discharge Resistance(Rd): 330 Ω±10%				
		5. Discharge, mode of operation Single Discharge (time between su (Tolerance if the output voltage in	accessive discharges at least 1 sec)			
		-30°C → +25°C →	+80°C → +25°C			
5	Temperature Cycling	4	(30mins) (5mins)			
5	Storage Test	10 Cycle				
		Surrounding temperature, then so	torage at normal condition 4hrs.			
		1. Sine wave 10∼55 Hz frequen	cy (1 min)			
6	Vibration Test	2. The amplitude of vibration :1.	5 mm			
	(Packaged)	3. Each direction (X \cdot Y \cdot Z) du	ration for 2 Hrs			
		Packing Weight (Kg)	Drop Height (cm)			
		0 ~ 45.4	122			
7	Drop Test	45.4 ~ 90.8	76			
7	Drop Test (Packaged)		76 61			

(800) 741-7755



5. PRECAUTION RELATING PRODUCT HANDLING 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI. When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

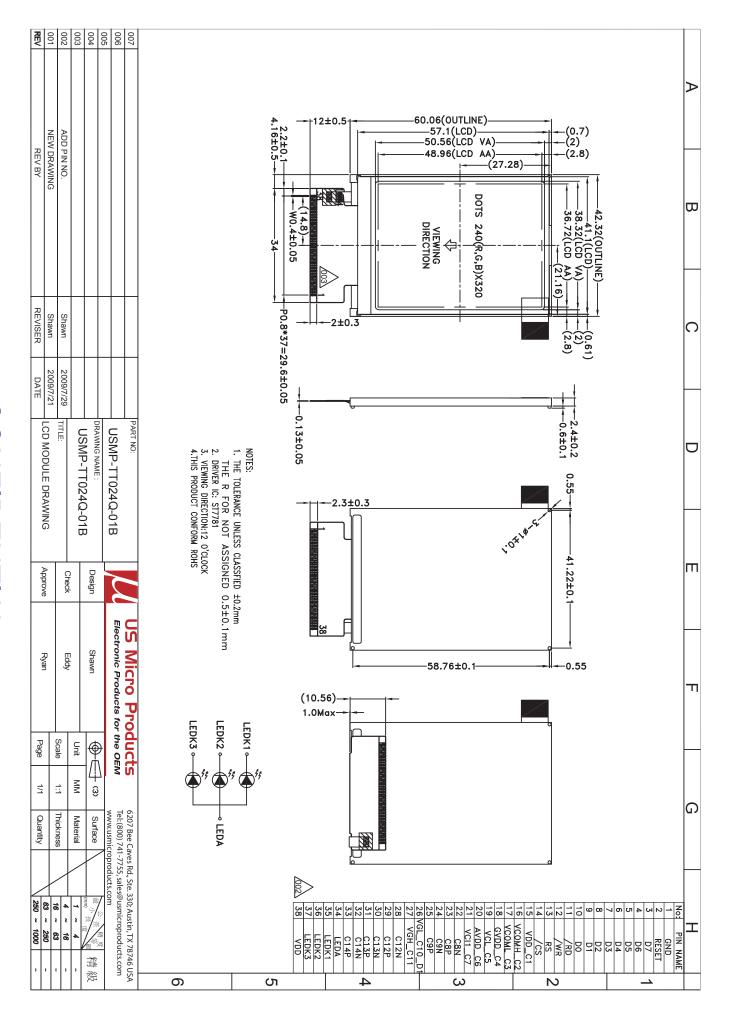
5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25°C ± 5°C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period
 - The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility
 - This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

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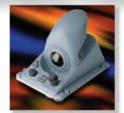
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Trackballs Aerospace Trackballs

Keyboards





Joysticks



Printers

